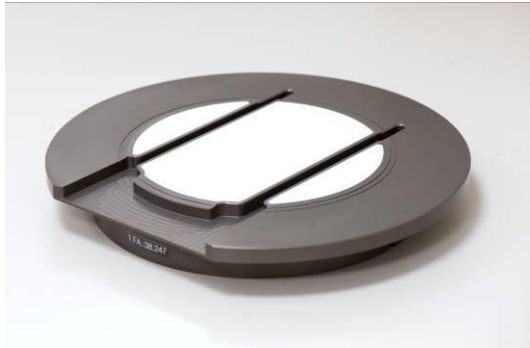


Thin wafer chuck

mV- Chuck Series



Features

- available for different wafer sizes (6"/8"/12")
- thin and warped wafer planarization
- special porous ceramic
- controlled vacuum flow

ASK FOR YOUR CUSTOMIZED SOLUTION!

Functional description

mechatronic vacuum chucks (mVC) are designed for secure placement of various wafer types (eg. standard, (ultra-)thin/warped, eWLB, Taiko, film-frame, MEMS) in a defined orientation. These chucks are mainly integrated in OEM-equipment (eg. for inspection measurement, defect detection, ...) under atmospheric conditions.

By using a special porous ceramic, the wafer is held on its backside without contacting the wafer chipside. The vacuum holding force is evenly spread on the entire backside surface to flatten the wafer.

Loading	Automated or manual from top side
Wafer detection	Vacuum
Centering accuracy (X, Y axis)	n.a.
Suitable End- effector	Top Grip End- effector, Contactless End- effector, Needle End- effector
Materials	Stainless steel, anodized aluminum, PEEK, NBR, porous ceramic;
Pneumatic	
Pneumatic media	Vacuum
Supply Vacuum	-85 kPa

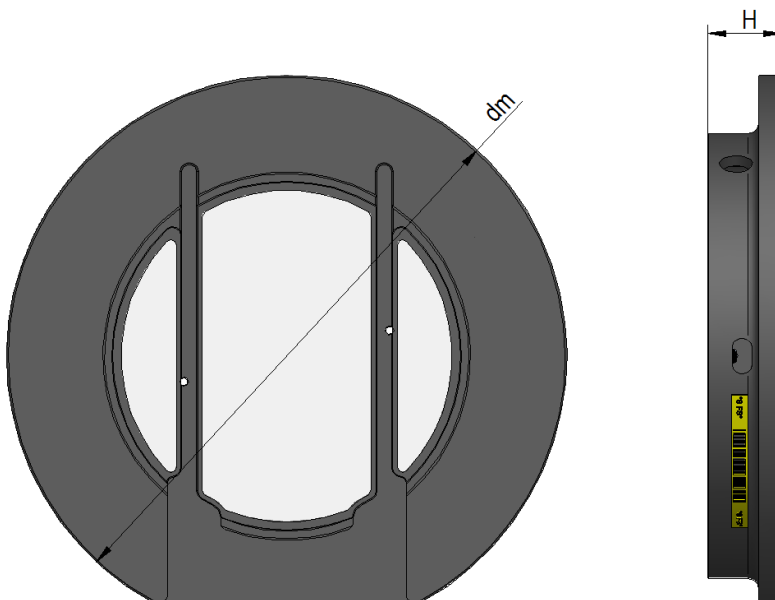
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Thin wafer chuck

mV- Chuck Types & sizes

Type	mV- Chuck 150	mV- Chuck 200	mV- Chuck 300
Wafer size	150 mm (6")	200 mm (8")	300 mm (12")
Wafer thickness	> 50 μm (2 mil)	> 50 μm (2 mil)	> 100 μm (4 mil)
Warpage (depends on wafer thickness)	Up to 4 mm	Up to 6 mm	Up to 10 mm
Weight	2920 g	2980 g	3650 g
Mechanical dimensions in mm			
dm (diameter)	305 mm	305 mm	308 mm
D (height)	40 mm	40 mm	40 mm

Special customized designs available!



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